## onsemi

## Product Bulletin Document #:PB25658X

Issue Date:27 Jul 2023

Title of Change:	NCD83591MNTXG Reticle Change with minor metal fill alteration + Die ID change			
Effective date:	27 Jul 2023			
Contact information:	Contact your local onsemi sales representative or Tristan Scott (Tristan.scott@onsemi.com)			
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.			
Change Category:	Wafer Fab Change			
Change Sub-Category(s):	Manufacturing Process Change			
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi, Gresham United States		None		
Description and Purpose:				

## Changing to higher volume reticle. As a result of this change, the Die ID has been changed + a small change was made in the metal fill for metal spacing optimization.

	From	То
Other Changes-Die ID	JORK-GOB0722	G0A07R2-J0W8
Other Changes-Metal spacing optimization	N/A	Minor metal fill change

## List of Affected Standard Parts:

**Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

NCD83591MNTXG